**R35-2010BB100R0Fx1QG**

**◆ Product Features**

<table>
<thead>
<tr>
<th>Case Size</th>
<th>Std. Resistance</th>
<th>Power</th>
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<tbody>
<tr>
<td>2010 mils</td>
<td>100Ω</td>
<td>250 mW</td>
</tr>
</tbody>
</table>

**◆ Specifications**

- **Operating Frequency**: DC to 50 GHz
- **Insertion Loss**: 6.0 dB ± 2dB typical
- **Operating Temperature Range**: 55°C to +150°C
- **Resistive Material**: Tantalum Nitride (TaN)
- **Temperature Coefficient**: ±150 ppm/°C standard
- **Resistance Tolerance**: ±1% (other tolerances available)
- **Substrate**: Alumina (Al₂O₃); other substrates available
- **Metallization**: A = Tantalum/Palladium/Gold (Ta/Pd/Au)  
  R = Titanium/Platinum/Gold (Ti/Pt/Au)

**◆ Packaging**

Parts are available in Waffle Packs and Tape & Reel. Contact PPI for additional packaging options.

**◆ Mechanical Dimensions**

<table>
<thead>
<tr>
<th>L</th>
<th>W</th>
<th>H</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.020” ± 0.002” (0.508mm ± 0.051mm)</td>
<td>0.010” ± 0.001” (0.254mm ± 0.051mm)</td>
<td>0.010” ± 0.001” (0.254mm ± 0.025mm)</td>
</tr>
</tbody>
</table>

**◆ Test Conditions**

Resistors were measured using 6.6 mil thick RO4350, using typical TRL calibration.

**◆ Part Numbering**

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R 35-2010 BB 100R0 F R1 Q G
```

- **Power Handling**: G = 250mW  
  TCR: Q = ±150ppm/°C
- **Metallization**: R = For Soldering; A = For wirebonding
- **Tolerance**: F = ±1%
- **Resistance Value**: 100Ω = 100R0; Digits 1-4 are significant; Digit 5 is number of zeros to follow
- **Broadband**: BB
- **Size**: .020” x .010”
- **Material**: 35 = Alumina
- **Resistor**

**Style: 1 – Recessed Pad**

Best for wire bonding or surface mount applications; compatible with Flip Chip configuration.